



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
(Case No. 207.008-US)

In the Application of: **LUTZ ET AL.**

)  
Group  
Art Unit:  
)  
Before  
Examiner

Serial No: **10/627,237**

Filed: **JULY 25, 2003**

Title: **ANCHORS FOR MICROELECTROMECHANICAL  
SYSTEMS HAVING AN SOI SUBSTRATE, AND  
METHOD OF FABRICATING SAME**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

I hereby certify that this correspondence  
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Patents, P.O. Box 1450, Alexandria, VA  
22313-1450 on October 24, 2003

Neil A. Steinberg  
(person signing this certificate)  
Neil A. Steinberg  
Signature

**FIRST INFORMATION DISCLOSURE STATEMENT**

Dear Sir:

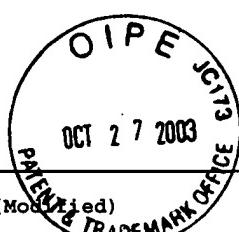
Submitted herewith are two (2) sheets of a modified Form PTO-1449. A copy of each document cited on the attached Form PTO-1449 is also submitted.

It is respectfully requested that the Examiner make his/her consideration of these documents formally of record with the initial Office Action.

Respectfully submitted,

Neil A. Steinberg  
Reg. No. 34,735  
650-968-8079

Date: October 24, 2003



Sheet 1 of 2

PTO-1449 (Modified)  U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE  INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.  207.008-US	SERIAL NUMBER  10/627,237
	APPLICANT(S)  Lutz et al.	
	FILING DATE  July 25, 2003	GROUP ART UNIT

U.S. PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE

FOREIGN PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO
	WO 01/77009	10/2001	PCT			
	WO 01/77008	10/2001	PCT			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	"Vacuum Sealing of Microcavities Using Metal Evaporation", Bartek et al., Sensors and Actuators A 61, 1997, pp.364-368
	"Vacuum Packaging Technology Using Localized Aluminum/Silicon-to-Glass Bonding", Cheng et al., MEMS 2001, 14 <sup>th</sup> IEEE International Conference, pp.18-21
	"A Hermetic Glass-Silicon Package Formed Using Localized Aluminum/Silicon-Glass Bonding", Cheng et al., Journal of Microelectromechanical Systems, Vol. 10, No. 3, Sept. 2001, pp.392-399
	"MEMS Post-Packaging by Localized Heating and Bonding", Lin, IEEE Transactions on Advanced Packaging, Vol. 23, No. 4, Nov. 2000, pp.608-616
	"Localized Silicon Fusion and Eutectic Bonding for MEMS Fabrication and Packaging", Cheng et al., Journal of Microelectromechanical Systems, Vol. 9, No. 1, March 2000, pp.3-8
	"Localized Bonding with PSG or Indium Solder as Intermediate Layer", Cheng et al., MEMS 1999, 12 <sup>th</sup> IEEE International Conference, pp.285-289
	"Vacuum encapsulation of resonant devices using permeable polysilicon", Lebouitz et al., Micro Electro Mechanical Systems, IEEE International Conference, Jan. 1999, pp.470-475
	"Electrical and optical characteristics of vacuum-sealed polysilicon microlamps", Mastrangelo et al., IEEE Transactions on Electron Devices, v.39, no.6, June 1992, pp.1363-1375
	"Vacuum-sealed silicon micromachined incandescent light source", Mastrangelo et al., IEDM, 1989, pp.503-506
	"Sealing of Micromachined Cavities Using Chemical Vapor Deposition Methods: Characterization and Optimization", Liu and Tai, IEEE Journal of Microelectromechanical Systems, Vol. 8, No. 2, June 1999, pp.135-145

EXAMINER	DATE CONSIDERED
EXAMINER: Initial citation if reference was considered. Draw line through citation if not in conformance to MPEP 609 and not considered. Include copy of this form with next communication to applicant.	



Sheet 2 of 2

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE  INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.  207.008-US	SERIAL NUMBER  10/627,237
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## FOREIGN PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	"Vacuum Packaging Technology Using Localized Aluminum/Silicon-to-Glass Bonding", Cheng et al., IEEE Journal of Microelectromechanical Systems, Vol. 11, No. 5, Oct. 2002, pp.556-565
	"Novel Process for a Monolithic Integrated Accelerometer", Offenberg et al., The 8 <sup>th</sup> International Conference on Solid-State Sensors and Actuators, and Eurosensors IX, Stockholm, Sweden, June 25-29, 1995, pp.589-592
	"An Integrated Wafer-Scale Packaging Process for MEMS", Kenny et al., Proceedings of IMECE2002, ASME International Mechanical Engineering Congress & Exposition, Nov. 17-22, 2002, New Orleans, Louisiana, pp.51-54
	"Polysilicon Vibrating Gyroscope Vacuum-Encapsulated in an on-chip Micro Chamber", Tsuchiya et al., Sensors and Actuators A 90 (2001), pp.49-55
	"New Thin Film Epitaxial Polysilicon Encapsulation for Piezoresistive Accelerometers", Partridge et al., IEEE, 2001, pp.54-59
	"A Low Temperature Bi-CMOS Compatible Process for MEMS RF Resonators and Filters", Lund et al., Solid-State Sensor, Actuator and Microsystems Workshop, Hilton Head Island, South Carolina, June 2-6, 2002, pp.38-41
	"Wafer Scale Encapsulation of a High-Q Micromechanical Resonator", Candler et al., Hilton Head, Open Poster, 2002

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